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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications,

Details

Product Status	Obsolete
Number of LABs/CLBs	1152
Number of Logic Elements/Cells	11520
Total RAM Bits	147456
Number of I/O	408
Number of Gates	728000
Voltage - Supply	1.71V ~ 1.89V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	652-BGA
Supplier Device Package	652-BGA (45x45)
Purchase URL	https://www.e-xfl.com/pro/item?MUrl=&PartUrl=ep20k300ebc652-1x

Table 8. Comparison of APEX 20K & APEX 20KE Features

Feature	APEX 20K Devices	APEX 20KE Devices
MultiCore system integration	Full support	Full support
SignalTap logic analysis	Full support	Full support
32/64-Bit, 33-MHz PCI	Full compliance in -1, -2 speed grades	Full compliance in -1, -2 speed grades
32/64-Bit, 66-MHz PCI	-	Full compliance in -1 speed grade
MultiVolt I/O	2.5-V or 3.3-V V_{CCIO} V_{CCIO} selected for device Certain devices are 5.0-V tolerant	1.8-V, 2.5-V, or 3.3-V V_{CCIO} V_{CCIO} selected block-by-block 5.0-V tolerant with use of external resistor
ClockLock support	Clock delay reduction 2 \times and 4 \times clock multiplication	Clock delay reduction $m/(n \times v)$ or $m/(n \times k)$ clock multiplication Drive ClockLock output off-chip External clock feedback ClockShift LVDS support Up to four PLLs ClockShift, clock phase adjustment
Dedicated clock and input pins	Six	Eight
I/O standard support	2.5-V, 3.3-V, 5.0-V I/O 3.3-V PCI Low-voltage complementary metal-oxide semiconductor (LVCMOS) Low-voltage transistor-to-transistor logic (LVTTL)	1.8-V, 2.5-V, 3.3-V, 5.0-V I/O 2.5-V I/O 3.3-V PCI and PCI-X 3.3-V Advanced Graphics Port (AGP) Center tap terminated (CTT) GTL+ LVCMOS LVTTL True-LVDS and LVPECL data pins (in EP20K300E and larger devices) LVDS and LVPECL signaling (in all BGA and FineLine BGA devices) LVDS and LVPECL data pins up to 156 Mbps (in -1 speed grade devices) HSTL Class I PCI-X SSTL-2 Class I and II SSTL-3 Class I and II
Memory support	Dual-port RAM FIFO RAM ROM	CAM Dual-port RAM FIFO RAM ROM

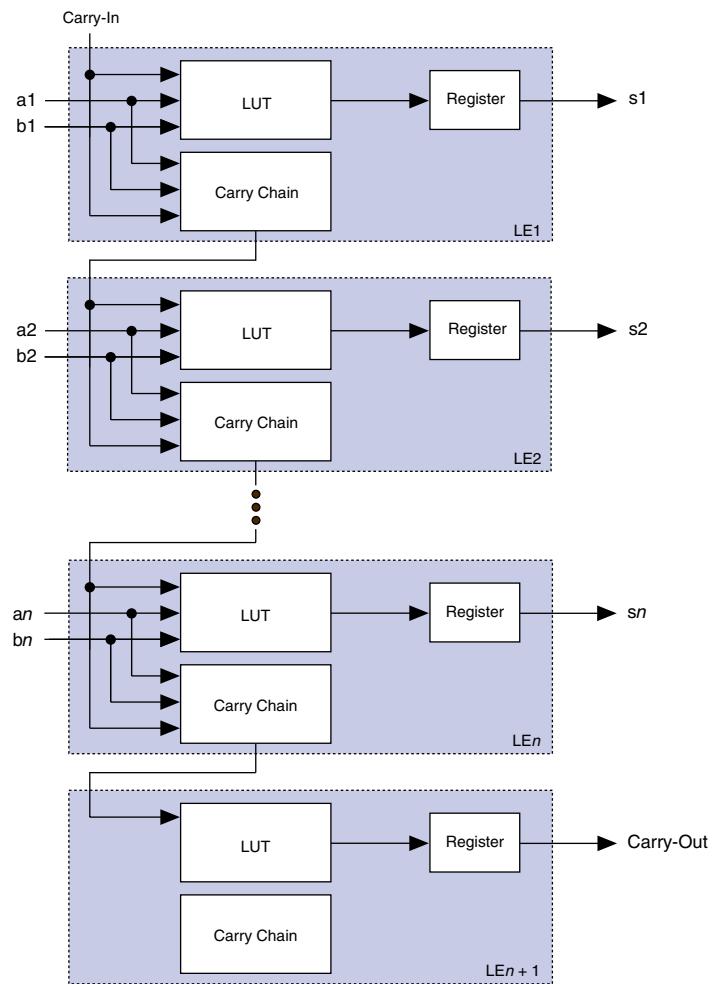
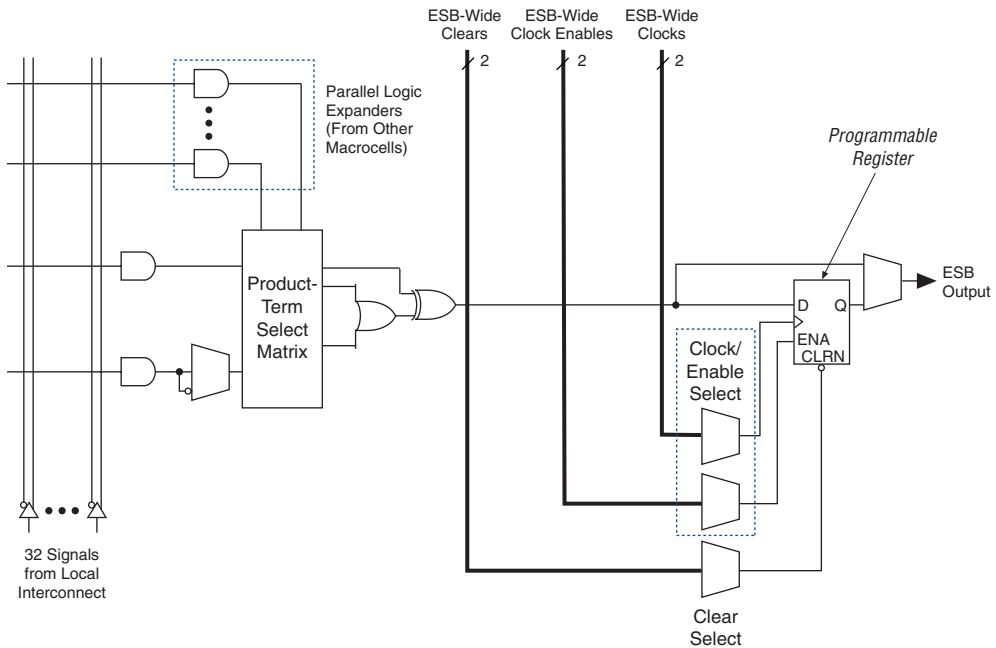
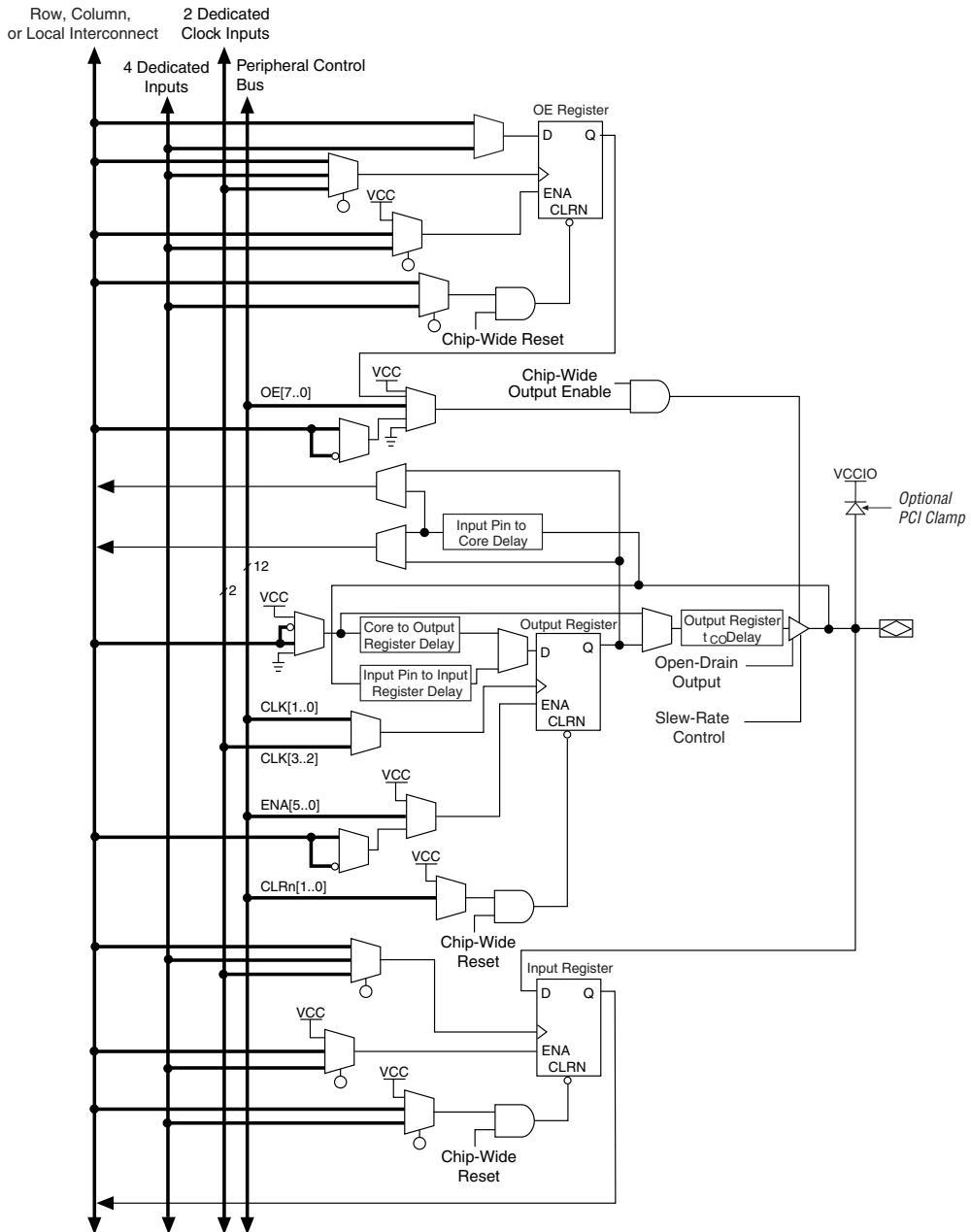
Figure 6. APEX 20K Carry Chain

Figure 14. APEX 20K Macrocell

For registered functions, each macrocell register can be programmed individually to implement D, T, JK, or SR operation with programmable clock control. The register can be bypassed for combinatorial operation. During design entry, the designer specifies the desired register type; the Quartus II software then selects the most efficient register operation for each registered function to optimize resource utilization. The Quartus II software or other synthesis tools can also select the most efficient register operation automatically when synthesizing HDL designs.

Each programmable register can be clocked by one of two ESB-wide clocks. The ESB-wide clocks can be generated from device dedicated clock pins, global signals, or local interconnect. Each clock also has an associated clock enable, generated from the local interconnect. The clock and clock enable signals are related for a particular ESB; any macrocell using a clock also uses the associated clock enable.

If both the rising and falling edges of a clock are used in an ESB, both ESB-wide clock signals are used.

Figure 25. APEX 20K Bidirectional I/O Registers Note (1)**Note to Figure 25:**

- (1) The output enable and input registers are LE registers in the LAB adjacent to the bidirectional pin.

Each IOE drives a row, column, MegaLAB, or local interconnect when used as an input or bidirectional pin. A row IOE can drive a local, MegaLAB, row, and column interconnect; a column IOE can drive the column interconnect. [Figure 27](#) shows how a row IOE connects to the interconnect.

Figure 27. Row IOE Connection to the Interconnect

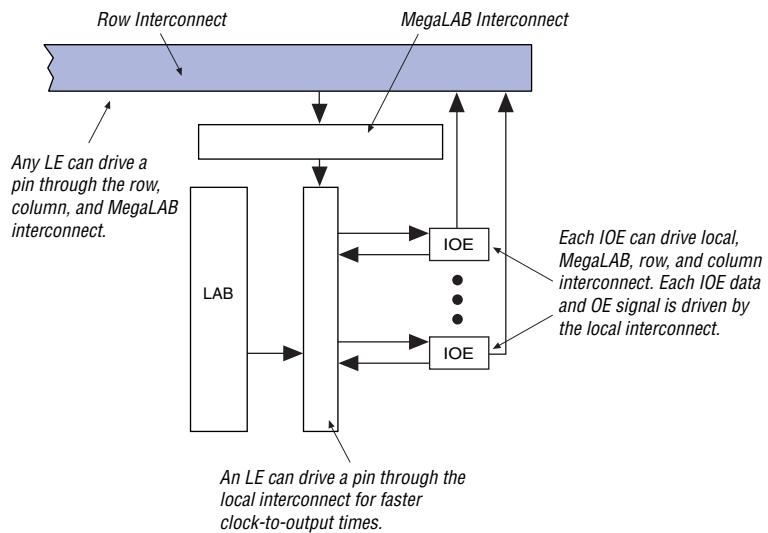
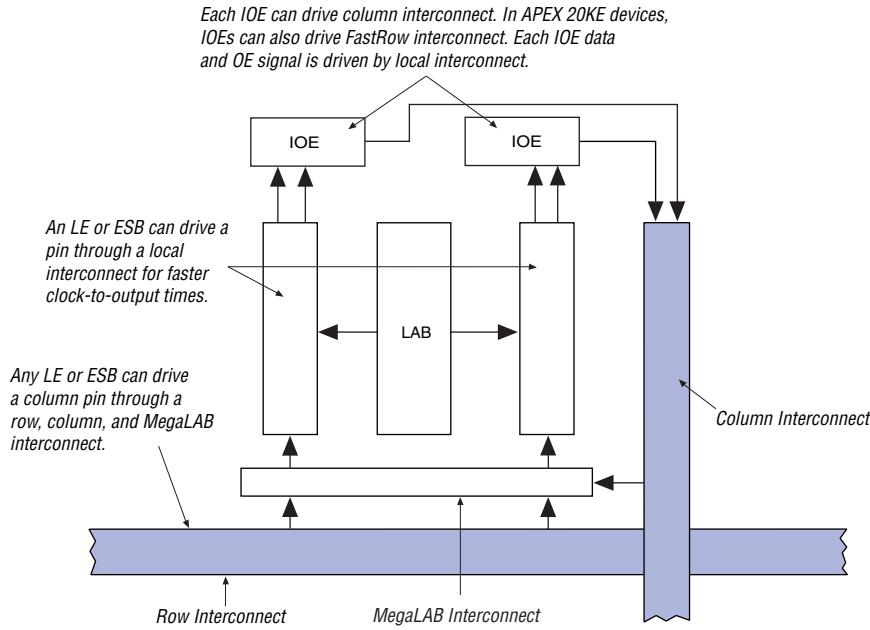


Figure 28 shows how a column IOE connects to the interconnect.

Figure 28. Column IOE Connection to the Interconnect



Dedicated Fast I/O Pins

APEX 20KE devices incorporate an enhancement to support bidirectional pins with high internal fanout such as PCI control signals. These pins are called Dedicated Fast I/O pins (FAST1, FAST2, FAST3, and FAST4) and replace dedicated inputs. These pins can be used for fast clock, clear, or high fanout logic signal distribution. They also can drive out. The Dedicated Fast I/O pin data output and tri-state control are driven by local interconnect from the adjacent MegaLAB for high speed.

Advanced I/O Standard Support

APEX 20KE IOEs support the following I/O standards: LVTTL, LVC MOS, 1.8-V I/O, 2.5-V I/O, 3.3-V PCI, PCI-X, 3.3-V AGP, LVDS, LVPECL, GTL+, CTT, HSTL Class I, SSTL-3 Class I and II, and SSTL-2 Class I and II.



For more information on I/O standards supported by APEX 20KE devices, see *Application Note 117 (Using Selectable I/O Standards in Altera Devices)*.

The APEX 20KE device contains eight I/O banks. In QFP packages, the banks are linked to form four I/O banks. The I/O banks directly support all standards except LVDS and LVPECL. All I/O banks can support LVDS and LVPECL with the addition of external resistors. In addition, one block within a bank contains circuitry to support high-speed True-LVDS and LVPECL inputs, and another block within a particular bank supports high-speed True-LVDS and LVPECL outputs. The LVDS blocks support all of the I/O standards. Each I/O bank has its own VCCIO pins. A single device can support 1.8-V, 2.5-V, and 3.3-V interfaces; each bank can support a different standard independently. Each bank can also use a separate V_{REF} level so that each bank can support any of the terminated standards (such as SSTL-3) independently. Within a bank, any one of the terminated standards can be supported. EP20K300E and larger APEX 20KE devices support the LVDS interface for data pins (smaller devices support LVDS clock pins, but not data pins). All EP20K300E and larger devices support the LVDS interface for data pins up to 155 Mbit per channel; EP20K400E devices and larger with an X-suffix on the ordering code add a serializer/deserializer circuit and PLL for higher-speed support.

Each bank can support multiple standards with the same VCCIO for output pins. Each bank can support one voltage-referenced I/O standard, but it can support multiple I/O standards with the same VCCIO voltage level. For example, when VCCIO is 3.3 V, a bank can support LVTTL, LVC MOS, 3.3-V PCI, and SSTL-3 for inputs and outputs.

When the LVDS banks are not used as LVDS I/O banks, they support all of the other I/O standards. [Figure 29](#) shows the arrangement of the APEX 20KE I/O banks.

Under hot socketing conditions, APEX 20KE devices will not sustain any damage, but the I/O pins will drive out.

MultiVolt I/O Interface

The APEX device architecture supports the MultiVolt I/O interface feature, which allows APEX devices in all packages to interface with systems of different supply voltages. The devices have one set of VCC pins for internal operation and input buffers (VCCINT), and another set for I/O output drivers (VCCIO).

The APEX 20K VCCINT pins must always be connected to a 2.5 V power supply. With a 2.5-V VCCINT level, input pins are 2.5-V, 3.3-V, and 5.0-V tolerant. The VCCIO pins can be connected to either a 2.5-V or 3.3-V power supply, depending on the output requirements. When VCCIO pins are connected to a 2.5-V power supply, the output levels are compatible with 2.5-V systems. When the VCCIO pins are connected to a 3.3-V power supply, the output high is 3.3 V and is compatible with 3.3-V or 5.0-V systems.

Table 12 summarizes 5.0-V tolerant APEX 20K MultiVolt I/O support.

Table 12. 5.0-V Tolerant APEX 20K MultiVolt I/O Support

V _{CCIO} (V)	Input Signals (V)			Output Signals (V)		
	2.5	3.3	5.0	2.5	3.3	5.0
2.5	✓	✓(1)	✓(1)	✓		
3.3	✓	✓	✓(1)	✓(2)	✓	✓

Notes to Table 12:

- (1) The PCI clamping diode must be disabled to drive an input with voltages higher than V_{CCIO}.
- (2) When V_{CCIO} = 3.3 V, an APEX 20K device can drive a 2.5-V device with 3.3-V tolerant inputs.

Open-drain output pins on 5.0-V tolerant APEX 20K devices (with a pull-up resistor to the 5.0-V supply) can drive 5.0-V CMOS input pins that require a V_{IH} of 3.5 V. When the pin is inactive, the trace will be pulled up to 5.0 V by the resistor. The open-drain pin will only drive low or tri-state; it will never drive high. The rise time is dependent on the value of the pull-up resistor and load impedance. The I_{OL} current specification should be considered when selecting a pull-up resistor.

Notes to Table 16:

- (1) To implement the ClockLock and ClockBoost circuitry with the Quartus II software, designers must specify the input frequency. The Quartus II software tunes the PLL in the ClockLock and ClockBoost circuitry to this frequency. The f_{CLKDEV} parameter specifies how much the incoming clock can differ from the specified frequency during device operation. Simulation does not reflect this parameter.
- (2) Twenty-five thousand parts per million (PPM) equates to 2.5% of input clock period.
- (3) During device configuration, the ClockLock and ClockBoost circuitry is configured before the rest of the device. If the incoming clock is supplied during configuration, the ClockLock and ClockBoost circuitry locks during configuration because the t_{LOCK} value is less than the time required for configuration.
- (4) The t_{JITTER} specification is measured under long-term observation.

Tables 17 and 18 summarize the ClockLock and ClockBoost parameters for APEX 20KE devices.

Table 17. APEX 20KE ClockLock & ClockBoost Parameters Note (1)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
t_R	Input rise time				5	ns
t_F	Input fall time				5	ns
t_{INDUTY}	Input duty cycle		40		60	%
$t_{INJITTER}$	Input jitter peak-to-peak				2% of input period	peak-to-peak
$t_{OUTJITTER}$	Jitter on ClockLock or ClockBoost-generated clock				0.35% of output period	RMS
$t_{OUTDUTY}$	Duty cycle for ClockLock or ClockBoost-generated clock		45		55	%
t_{LOCK} (2), (3)	Time required for ClockLock or ClockBoost to acquire lock				40	μs

Table 18. APEX 20KE Clock Input & Output Parameters (Part 1 of 2) Note (1)

Symbol	Parameter	I/O Standard	-1X Speed Grade		-2X Speed Grade		Units
			Min	Max	Min	Max	
f _{VCO} (4)	Voltage controlled oscillator operating range		200	500	200	500	MHz
f _{CLOCK0}	Clock0 PLL output frequency for internal use		1.5	335	1.5	200	MHz
f _{CLOCK1}	Clock1 PLL output frequency for internal use		20	335	20	200	MHz
f _{CLOCK0_EXT}	Output clock frequency for external clock0 output	3.3-V LVTTL	1.5	245	1.5	226	MHz
		2.5-V LVTTL	1.5	234	1.5	221	MHz
		1.8-V LVTTL	1.5	223	1.5	216	MHz
		GTL+	1.5	205	1.5	193	MHz
		SSTL-2 Class I	1.5	158	1.5	157	MHz
		SSTL-2 Class II	1.5	142	1.5	142	MHz
		SSTL-3 Class I	1.5	166	1.5	162	MHz
		SSTL-3 Class II	1.5	149	1.5	146	MHz
		LVDS	1.5	420	1.5	350	MHz
f _{CLOCK1_EXT}	Output clock frequency for external clock1 output	3.3-V LVTTL	20	245	20	226	MHz
		2.5-V LVTTL	20	234	20	221	MHz
		1.8-V LVTTL	20	223	20	216	MHz
		GTL+	20	205	20	193	MHz
		SSTL-2 Class I	20	158	20	157	MHz
		SSTL-2 Class II	20	142	20	142	MHz
		SSTL-3 Class I	20	166	20	162	MHz
		SSTL-3 Class II	20	149	20	146	MHz
		LVDS	20	420	20	350	MHz

Table 21. 32-Bit APEX 20K Device IDCODE

Device	IDCODE (32 Bits) (1)			
	Version (4 Bits)	Part Number (16 Bits)	Manufacturer Identity (11 Bits)	1 (1 Bit) (2)
EP20K30E	0000	1000 0000 0011 0000	000 0110 1110	1
EP20K60E	0000	1000 0000 0110 0000	000 0110 1110	1
EP20K100	0000	0000 0100 0001 0110	000 0110 1110	1
EP20K100E	0000	1000 0001 0000 0000	000 0110 1110	1
EP20K160E	0000	1000 0001 0110 0000	000 0110 1110	1
EP20K200	0000	0000 1000 0011 0010	000 0110 1110	1
EP20K200E	0000	1000 0010 0000 0000	000 0110 1110	1
EP20K300E	0000	1000 0011 0000 0000	000 0110 1110	1
EP20K400	0000	0001 0110 0110 0100	000 0110 1110	1
EP20K400E	0000	1000 0100 0000 0000	000 0110 1110	1
EP20K600E	0000	1000 0110 0000 0000	000 0110 1110	1
EP20K1000E	0000	1001 0000 0000 0000	000 0110 1110	1

Notes to Table 21:

- (1) The most significant bit (MSB) is on the left.
- (2) The IDCODE's least significant bit (LSB) is always 1.

Figure 31 shows the timing requirements for the JTAG signals.

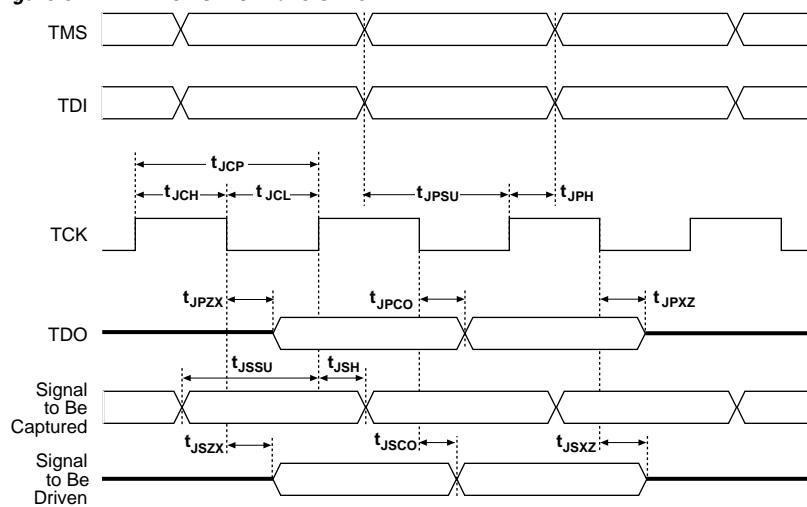
Figure 31. APEX 20K JTAG Waveforms

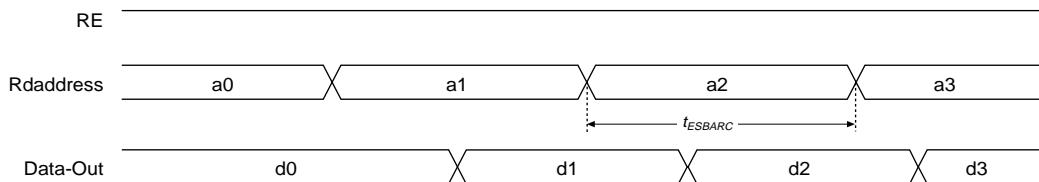
Table 29. APEX 20KE Device DC Operating Conditions *Notes (7), (8), (9)*

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{IH}	High-level LVTTL, CMOS, or 3.3-V PCI input voltage		1.7, 0.5 $\times V_{CCIO}$ <i>(10)</i>		4.1	V
V_{IL}	Low-level LVTTL, CMOS, or 3.3-V PCI input voltage		-0.5		0.8, 0.3 $\times V_{CCIO}$ <i>(10)</i>	V
V_{OH}	3.3-V high-level LVTTL output voltage	$I_{OH} = -12 \text{ mA DC}$, $V_{CCIO} = 3.00 \text{ V}$ <i>(11)</i>	2.4			V
	3.3-V high-level LVCMOS output voltage	$I_{OH} = -0.1 \text{ mA DC}$, $V_{CCIO} = 3.00 \text{ V}$ <i>(11)</i>	$V_{CCIO} - 0.2$			V
	3.3-V high-level PCI output voltage	$I_{OH} = -0.5 \text{ mA DC}$, $V_{CCIO} = 3.00 \text{ to } 3.60 \text{ V}$ <i>(11)</i>	$0.9 \times V_{CCIO}$			V
	2.5-V high-level output voltage	$I_{OH} = -0.1 \text{ mA DC}$, $V_{CCIO} = 2.30 \text{ V}$ <i>(11)</i>	2.1			V
		$I_{OH} = -1 \text{ mA DC}$, $V_{CCIO} = 2.30 \text{ V}$ <i>(11)</i>	2.0			V
		$I_{OH} = -2 \text{ mA DC}$, $V_{CCIO} = 2.30 \text{ V}$ <i>(11)</i>	1.7			V
V_{OL}	3.3-V low-level LVTTL output voltage	$I_{OL} = 12 \text{ mA DC}$, $V_{CCIO} = 3.00 \text{ V}$ <i>(12)</i>			0.4	V
	3.3-V low-level LVCMOS output voltage	$I_{OL} = 0.1 \text{ mA DC}$, $V_{CCIO} = 3.00 \text{ V}$ <i>(12)</i>			0.2	V
	3.3-V low-level PCI output voltage	$I_{OL} = 1.5 \text{ mA DC}$, $V_{CCIO} = 3.00 \text{ to } 3.60 \text{ V}$ <i>(12)</i>			$0.1 \times V_{CCIO}$	V
	2.5-V low-level output voltage	$I_{OL} = 0.1 \text{ mA DC}$, $V_{CCIO} = 2.30 \text{ V}$ <i>(12)</i>			0.2	V
		$I_{OL} = 1 \text{ mA DC}$, $V_{CCIO} = 2.30 \text{ V}$ <i>(12)</i>			0.4	V
		$I_{OL} = 2 \text{ mA DC}$, $V_{CCIO} = 2.30 \text{ V}$ <i>(12)</i>			0.7	V
I_I	Input pin leakage current	$V_I = 4.1 \text{ to } -0.5 \text{ V}$ <i>(13)</i>	-10		10	μA
I_{IOZ}	Tri-stated I/O pin leakage current	$V_O = 4.1 \text{ to } -0.5 \text{ V}$ <i>(13)</i>	-10		10	μA
I_{CC0}	V _{CC} supply current (standby) (All ESBs in power-down mode)	$V_I = \text{ground, no load, no toggling inputs, -1 speed grade}$		10		mA
		$V_I = \text{ground, no load, no toggling inputs, -2, -3 speed grades}$		5		mA
R_{CONF}	Value of I/O pin pull-up resistor before and during configuration	$V_{CCIO} = 3.0 \text{ V}$ <i>(14)</i>	20		50	k Ω
		$V_{CCIO} = 2.375 \text{ V}$ <i>(14)</i>	30		80	k Ω
		$V_{CCIO} = 1.71 \text{ V}$ <i>(14)</i>	60		150	k Ω

Figures 38 and 39 show the asynchronous and synchronous timing waveforms, respectively, for the ESB macroparameters in Table 31.

Figure 38. ESB Asynchronous Timing Waveforms

ESB Asynchronous Read



ESB Asynchronous Write

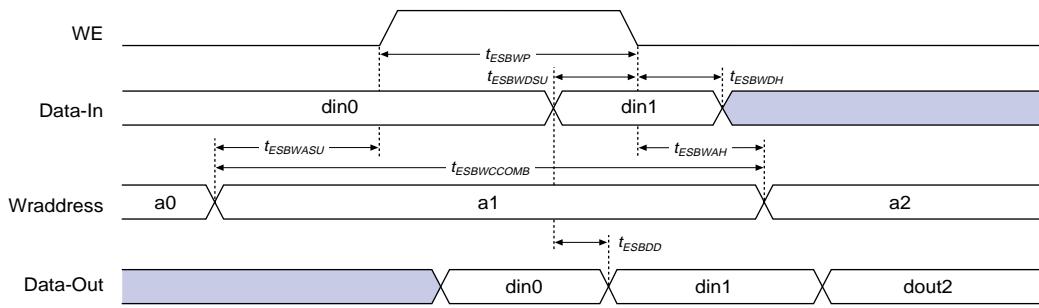


Table 31. APEX 20K f_{MAX} Timing Parameters (Part 2 of 2)

Symbol	Parameter
$t_{ESBDA}CO_2$	ESB clock-to-output delay without output registers
t_{ESBDD}	ESB data-in to data-out delay for RAM mode
t_{PD}	ESB macrocell input to non-registered output
$t_{PTERMSU}$	ESB macrocell register setup time before clock
$t_{PTERMCO}$	ESB macrocell register clock-to-output delay
t_{F1-4}	Fanout delay using local interconnect
t_{F5-20}	Fanout delay using MegaLab Interconnect
t_{F20+}	Fanout delay using FastTrack Interconnect
t_{CH}	Minimum clock high time from clock pin
t_{CL}	Minimum clock low time from clock pin
t_{CLR}	LE clear pulse width
t_{PREP}	LE preset pulse width
t_{ESBCH}	Clock high time
t_{ESBCL}	Clock low time
t_{ESBWP}	Write pulse width
t_{ESBRP}	Read pulse width

Tables 32 and 33 describe APEX 20K external timing parameters.

Table 32. APEX 20K External Timing Parameters Note (1)

Symbol	Clock Parameter
t_{INSU}	Setup time with global clock at IOE register
t_{INH}	Hold time with global clock at IOE register
t_{OUTCO}	Clock-to-output delay with global clock at IOE register

Table 33. APEX 20K External Bidirectional Timing Parameters Note (1)

Symbol	Parameter	Conditions
$t_{INSUBIDIR}$	Setup time for bidirectional pins with global clock at same-row or same-column LE register	
$t_{INHBIDIR}$	Hold time for bidirectional pins with global clock at same-row or same-column LE register	
$t_{OUTCOBIDIR}$	Clock-to-output delay for bidirectional pins with global clock at IOE register	$C_1 = 10 \text{ pF}$
$t_{ZXBIDIR}$	Synchronous IOE output buffer disable delay	$C_1 = 10 \text{ pF}$
$t_{ZXBIDIR}$	Synchronous IOE output buffer enable delay, slow slew rate = off	$C_1 = 10 \text{ pF}$

Table 52. EP20K30E Minimum Pulse Width Timing Parameters

Symbol	-1		-2		-3		Unit
	Min	Max	Min	Max	Min	Max	
t _{CH}	0.55		0.78		1.15		ns
t _{CL}	0.55		0.78		1.15		ns
t _{CLRP}	0.22		0.31		0.46		ns
t _{PREP}	0.22		0.31		0.46		ns
t _{ESBCH}	0.55		0.78		1.15		ns
t _{ESBCL}	0.55		0.78		1.15		ns
t _{ESBWP}	1.43		2.01		2.97		ns
t _{ESBRP}	1.15		1.62		2.39		ns

Table 53. EP20K30E External Timing Parameters

Symbol	-1		-2		-3		Unit
	Min	Max	Min	Max	Min	Max	
t _{INSU}	2.02		2.13		2.24		ns
t _{INH}	0.00		0.00		0.00		ns
t _{OUTCO}	2.00	4.88	2.00	5.36	2.00	5.88	ns
t _{INSUPLL}	2.11		2.23		-		ns
t _{INHPPLL}	0.00		0.00		-		ns
t _{OUTCOPLL}	0.50	2.60	0.50	2.88	-	-	ns

Table 54. EP20K30E External Bidirectional Timing Parameters

Symbol	-1		-2		-3		Unit
	Min	Max	Min	Max	Min	Max	
t _{INSUBIDIR}	1.85		1.77		1.54		ns
t _{INHBIDIR}	0.00		0.00		0.00		ns
t _{OUTCOBIDIR}	2.00	4.88	2.00	5.36	2.00	5.88	ns
t _{XZBIDIR}		7.48		8.46		9.83	ns
t _{ZXBIDIR}		7.48		8.46		9.83	ns
t _{INSUBIDIRPLL}	4.12		4.24		-		ns
t _{INHBIDIRPLL}	0.00		0.00		-		ns
t _{OUTCOBIDIRPLL}	0.50	2.60	0.50	2.88	-	-	ns
t _{XZBIDIRPLL}		5.21		5.99		-	ns
t _{ZXBIDIRPLL}		5.21		5.99		-	ns

Table 69. EP20K160E f_{MAX} Routing Delays

Symbol	-1		-2		-3		Unit
	Min	Max	Min	Max	Min	Max	
t_{F1-4}		0.25		0.26		0.28	ns
t_{F5-20}		1.00		1.18		1.35	ns
t_{F20+}		1.95		2.19		2.30	ns

Table 70. EP20K160E Minimum Pulse Width Timing Parameters

Symbol	-1		-2		-3		Unit
	Min	Max	Min	Max	Min	Max	
t_{CH}	1.34		1.43		1.55		ns
t_{CL}	1.34		1.43		1.55		ns
t_{CLRP}	0.18		0.19		0.21		ns
t_{PREP}	0.18		0.19		0.21		ns
t_{ESBCH}	1.34		1.43		1.55		ns
t_{ESBCL}	1.34		1.43		1.55		ns
t_{ESBWP}	1.15		1.45		1.73		ns
t_{ESBRP}	0.93		1.15		1.38		ns

Table 71. EP20K160E External Timing Parameters

Symbol	-1		-2		-3		Unit
	Min	Max	Min	Max	Min	Max	
t_{INSU}	2.23		2.34		2.47		ns
t_{INH}	0.00		0.00		0.00		ns
t_{OUTCO}	2.00	5.07	2.00	5.59	2.00	6.13	ns
$t_{INSUPLL}$	2.12		2.07		-		ns
t_{INHPLL}	0.00		0.00		-		ns
$t_{OUTCOPLL}$	0.50	3.00	0.50	3.35	-	-	ns

Table 90. EP20K400E External Bidirectional Timing Parameters

Symbol	-1 Speed Grade		-2 Speed Grade		-3 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	
t _{INSUBIDIR}	2.93		3.23		3.44		ns
t _{INHBIDIR}	0.00		0.00		0.00		ns
t _{OUTCOBIDIR}	2.00	5.25	2.00	5.79	2.00	6.32	ns
t _{XZBIDIR}		5.95		6.77		7.12	ns
t _{ZXBIDIR}		5.95		6.77		7.12	ns
t _{INSUBIDIRPLL}	4.31		4.76		-		ns
t _{INHBIDIRPLL}	0.00		0.00		-		ns
t _{OUTCOBIDIRPLL}	0.50	2.25	0.50	2.45	-	-	ns
t _{XZBIDIRPLL}		2.94		3.43		-	ns
t _{ZXBIDIRPLL}		2.94		3.43		-	ns

Tables 91 through 96 describe f_{MAX} LE Timing Microparameters, f_{MAX} ESB Timing Microparameters, f_{MAX} Routing Delays, Minimum Pulse Width Timing Parameters, External Timing Parameters, and External Bidirectional Timing Parameters for EP20K600E APEX 20KE devices.

Table 91. EP20K600E f_{MAX} LE Timing Microparameters

Symbol	-1 Speed Grade		-2 Speed Grade		-3 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	
t _{SU}	0.16		0.16		0.17		ns
t _H	0.29		0.33		0.37		ns
t _{CO}		0.65		0.38		0.49	ns
t _{LUT}		0.70		1.00		1.30	ns

Table 92. EP20K600E f_{MAX} ESB Timing Microparameters

Symbol	-1 Speed Grade		-2 Speed Grade		-3 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	
t_{ESBARC}		1.67		2.39		3.11	ns
t_{ESBSRC}		2.27		3.07		3.86	ns
t_{ESBAWC}		3.19		4.56		5.93	ns
t_{ESBSWC}		3.51		4.62		5.72	ns
$t_{ESBWASU}$	1.46		2.08		2.70		ns
t_{ESBWAH}	0.00		0.00		0.00		ns
$t_{ESBWDSU}$	1.60		2.29		2.97		ns
t_{ESBWDH}	0.00		0.00		0.00		ns
$t_{ESBRASU}$	1.61		2.30		2.99		ns
t_{ESBRAH}	0.00		0.00		0.00		ns
$t_{ESBWESU}$	1.49		2.30		3.11		ns
t_{ESBWEH}	0.00		0.00		0.00		ns
$t_{ESBDATASU}$	-0.01		0.35		0.71		ns
$t_{ESBDAZH}$	0.13		0.13		0.13		ns
$t_{ESBWADDRSU}$	0.19		0.62		1.06		ns
$t_{ESBRADDRSU}$	0.25		0.71		1.17		ns
$t_{ESBDAZCO1}$		1.01		1.19		1.37	ns
$t_{ESBDAZCO2}$		2.18		3.12		4.05	ns
t_{ESBDD}		3.19		4.56		5.93	ns
t_{PD}		1.57		2.25		2.92	ns
$t_{PTERMSU}$	0.85		1.43		2.01		ns
$t_{PTERMCO}$		1.03		1.21		1.39	ns

Table 93. EP20K600E f_{MAX} Routing Delays

Symbol	-1 Speed Grade		-2 Speed Grade		-3 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	
t_{F1-4}		0.22		0.25		0.26	ns
t_{F5-20}		1.26		1.39		1.52	ns
t_{F20+}		3.51		3.88		4.26	ns

Table 94. EP20K600E Minimum Pulse Width Timing Parameters

Symbol	-1 Speed Grade		-2 Speed Grade		-3 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	
t _{CH}	2.00		2.50		2.75		ns
t _{CL}	2.00		2.50		2.75		ns
t _{CLRP}	0.18		0.26		0.34		ns
t _{PREP}	0.18		0.26		0.34		ns
t _{ESBCH}	2.00		2.50		2.75		ns
t _{ESBCL}	2.00		2.50		2.75		ns
t _{ESBWP}	1.17		1.68		2.18		ns
t _{ESBRP}	0.95		1.35		1.76		ns

Table 95. EP20K600E External Timing Parameters

Symbol	-1 Speed Grade		-2 Speed Grade		-3 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	
t _{INSU}	2.74		2.74		2.87		ns
t _{INH}	0.00		0.00		0.00		ns
t _{OUTCO}	2.00	5.51	2.00	6.06	2.00	6.61	ns
t _{INSUPLL}	1.86		1.96		-		ns
t _{INHPLL}	0.00		0.00		-		ns
t _{OUTCOPLL}	0.50	2.62	0.50	2.91	-	-	ns

Table 96. EP20K600E External Bidirectional Timing Parameters

Symbol	-1 Speed Grade		-2 Speed Grade		-3 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	
t _{INSUBIDIR}	0.64		0.98		1.08		ns
t _{INHBIDIR}	0.00		0.00		0.00		ns
t _{OUTCOBIDIR}	2.00	5.51	2.00	6.06	2.00	6.61	ns
t _{XZBIDIR}		6.10		6.74		7.10	ns
t _{ZXBIDIR}		6.10		6.74		7.10	ns
t _{INSUBIDIRPLL}	2.26		2.68		-		ns
t _{INHBIDIRPLL}	0.00		0.00		-		ns
t _{OUTCOBIDIRPLL}	0.50	2.62	0.50	2.91	-	-	ns
t _{XZBIDIRPLL}		3.21		3.59		-	ns
t _{ZXBIDIRPLL}		3.21		3.59		-	ns

Table 98. EP20K1000E f_{MAX} ESB Timing Microparameters

Symbol	-1 Speed Grade		-2 Speed Grade		-3 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	
t _{ESBARC}		1.78		2.02		1.95	ns
t _{ESBSRC}		2.52		2.91		3.14	ns
t _{ESBAWC}		3.52		4.11		4.40	ns
t _{ESBSWC}		3.23		3.84		4.16	ns
t _{ESBWASU}	0.62		0.67		0.61		ns
t _{ESBWAH}	0.41		0.55		0.55		ns
t _{ESBWDSU}	0.77		0.79		0.81		ns
t _{ESBWDH}	0.41		0.55		0.55		ns
t _{ESBRASU}	1.74		1.92		1.85		ns
t _{ESBRAH}	0.00		0.01		0.23		ns
t _{ESBWESU}	2.07		2.28		2.41		ns
t _{ESBWEH}	0.00		0.00		0.00		ns
t _{ESBDATASU}	0.25		0.27		0.29		ns
t _{ESBDATAH}	0.13		0.13		0.13		ns
t _{ESBWADDRSU}	0.11		0.04		0.11		ns
t _{ESBRADDRSU}	0.14		0.11		0.16		ns
t _{ESBDAACO1}		1.29		1.50		1.63	ns
t _{ESBDAACO2}		2.55		2.99		3.22	ns
t _{ESBDD}		3.12		3.57		3.85	ns
t _{PD}		1.84		2.13		2.32	ns
t _{PTERMSU}	1.08		1.19		1.32		ns
t _{PTERMCO}		1.31		1.53		1.66	ns